

# HSF

**NOTES:**

Current Rating: 1.0AMP  
 Contact Resistance: 20mΩ Max  
 Withstand Voltage: 500V AC/DC  
 Insulation Resistance: 1000MΩ Min  
 Operation Temperature: -40°C to +105°C

Contact Material: Brass  
 Contact plating: Au Or Sn over Ni  
 Insulator Material: PA9T+30%G.F UL94V-0

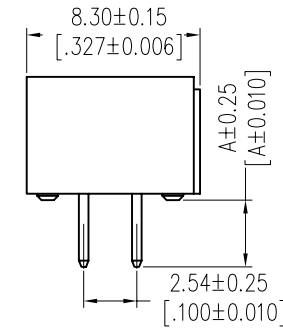
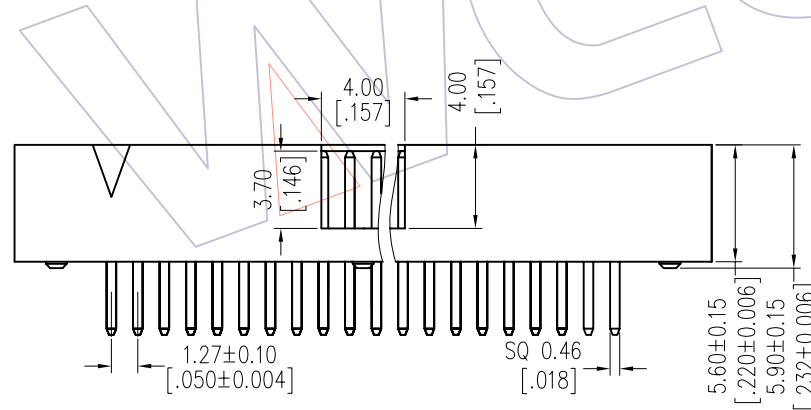
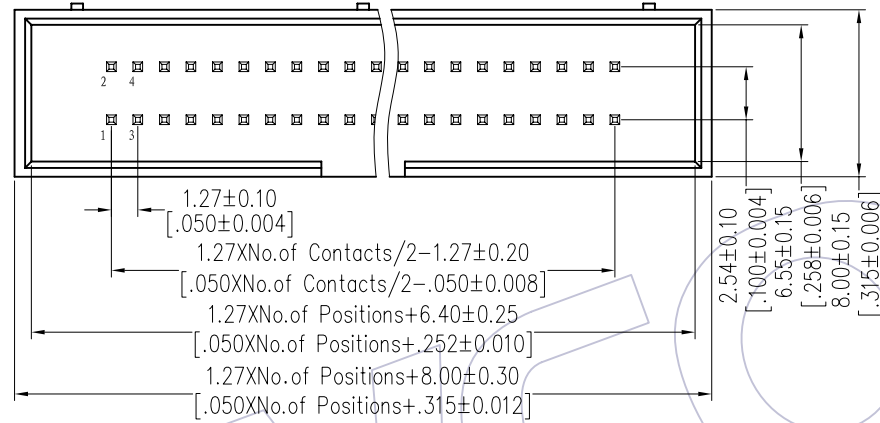
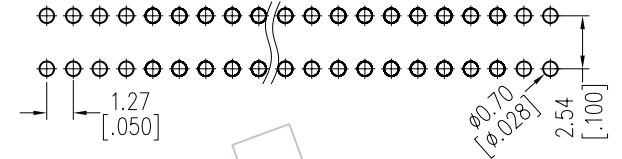
## Ordering Information

3140-XX S XX B K00 X 1

No. of Pins	Contact Plating	Color Insulator	Packing
10 34	G0=Gold Flash	B=Black	T=Tube
14 40	G3=10u"Gold	W=White	
16 44	G4=15u"Gold		
20 50	G5=30u"Gold		
24 60	S0=Gold Flash/Tin		
26 64	S3=10u"Gold/Tin		
30 80	S4=15u"Gold/Tin		
100	S5=30u"Gold/Tin		
	SN=Tin		

Item	Pitch	Mating	Dip(A)
Standard	1.27X2.54	5242	3.20
Alternate			

Recommended P.C.B Layout(Top Side)  
 (PCB BOARD TOLERANCE±0.05)



OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
x.x ±0.40	JYHuang	2012/09/18	UNIT mm		3140-XXSXXBK00X1
x.xx ±0.25	CHECK	DATE	SIZE A4		TITLE: 1.27x2.54 BOX HEADER 180° H=5.9
x.xxx ±0.15	APPROVE	DATE	SHEET 1/1		Customer NO.
Angle ± 3'			PROJ.		
DIM TOL					

REV	DATE	MODIFICATION DESCRIPTION	CHANGE
A0	2012/09/18	NEW	-----